

Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) An electronic device comprising:

a substrate on which an interconnect pattern is formed;

a chip component having a base material and having a first surface on which a pad is formed and a second surface opposite to the first surface; the chip component being mounted in such a manner that the second surface faces the substrate;

a metal layer formed of a plurality of layers including a diffusion prevention layer in contact with the pad and an uppermost layer being less oxidizable than the pad, the diffusion prevention layer preventing any diffusion of material formed thereabove into the base material of the chip component;

an insulating section formed above and adjacent to the chip component, the insulating section having ~~an inclined surface descending in an outward direction from the chip component, the inclined surface being~~ a convex surface that draws a curve on a view from which a cross section perpendicular to the first surface of the chip component is ~~taken;~~ taken, the convex surface ascending from the first surface to have a top surface and descending from the top surface in an outward direction, the insulating section having a portion above the first surface that has a lower surface than the top surface; and

an interconnect which is formed to extend from above the uppermost layer of the metal layer, over the insulating section and to above the interconnect pattern, the interconnect covering all the lateral surfaces of the metal layer.

2. (Original) The electronic device as defined by claim 1,
wherein the insulating section is formed of resin.
3. (Currently Amended) The electronic device as defined by claim 1,

further comprising a passivation film formed on the first surface of the chip component, the passivation film formed to avoid at least a part of the ~~electrode, pad,~~

wherein the portion of the insulating section has a portion above the first surface sits on the passivation film.

4. (Previously Presented) The electronic device as defined by claim 1, further comprising a connecting layer disposed between the chip component and the substrate,

wherein the insulating section is formed of the same material as the connecting layer.

5. (Currently Amended) A method of manufacturing an electronic device, the method comprising:

mounting a chip component having a base material and having a pad on a substrate on which an interconnect pattern is formed, in such a manner that a second surface faces the substrate, the pad being formed on a first surface and the second surface being opposite to the first surface;

forming a metal layer of a plurality of layers including a diffusion prevention layer in contact with the pad and an uppermost layer being less oxidizable than the pad, the diffusion prevention layer preventing any diffusion of material formed thereabove into the base material of the chip component;

forming an insulating section above and adjacent to the chip component to ~~have an inclined surface descending in an outward direction from the chip component, the inclined surface being~~ a convex surface that draws a curve on a view from which a cross section perpendicular to the first surface of the chip component is ~~taken;~~ taken, the convex surface ascending from the first surface to have a top surface and descending from the top

surface in an outward direction, the insulating section having a portion above the first surface that has a lower surface than the top surface; and

forming an interconnect in such a manner as to extend from above the uppermost layer of the metal layer, over the insulating section and to above the interconnect pattern, and as to cover all the lateral surfaces of the metal layer.

6. (Original) The method of manufacturing an electronic device as defined by claim 5,

wherein the interconnect is formed of a dispersant including electrically conductive particles.

7. (Original) The method of manufacturing an electronic device as defined by claim 6,

wherein the step of forming the interconnect includes ejecting the dispersant including the electrically conductive particles over the metal layer, the insulating section and the interconnect pattern.

8. (Original) The method of manufacturing an electronic device as defined by claim 5,

wherein the insulating section is formed of a resin.

9. (Original) The method of manufacturing an electronic device as defined by claim 6,

wherein the insulating section is formed of a resin.

10. (Original) The method of manufacturing an electronic device as defined by claim 7,

wherein the insulating section is formed of a resin.

11. (Currently Amended) The method of manufacturing an electronic device as defined by claim 5,

further comprising forming a passivation film on the first surface of the chip component so as to avoid at least a part of the ~~electrode pad~~,

wherein the portion of the insulating section above the first surface is formed ~~to have a portion~~ on the passivation film.

12. (Previously Presented) The method of manufacturing an electronic device as defined by claim 5,

further comprising disposing a connecting layer between the chip component and the substrate,

wherein the insulating section is formed of the same material as the connecting layer.

13-16. (Canceled)

17. (Original) A circuit board on which the electronic device defined by claim 1 is mounted.

18. (Original) An electronic instrument having the electronic device defined by claim 1.